



# 50-3120 SINGLE COMPONENT THERMALLY CONDUCTIVE EPOXY

## DESCRIPTION:

50-3120 is a filled, single component, thermally conductive, electrically insulating epoxy system. This material is thixotropic and designed for the placement of SMD's on printed circuit boards or other substrates prior to wave soldering. It may also be used in heat sink applications.

50-3120 has a soft, very smooth consistency and will therefore not "run" once applied. It is easily dispensed through fine gauge needles.

## TYPICAL SPECIFICATIONS:

Viscosity	Soft Creamy Paste
Specific Gravity, @25 C	1.85
Tensile Strength, psi	7,500
Pot Life, 100 gram mass @ 25°C	Single Component
Hardness, Shore D	80
Cure Temperature	15 Minutes at 100°C 5 Minutes at 150°C 2 Minutes at 175°C
Shelf Life	25°C 4-6 Months 0°C 12 Months
Thermal Conductivity, BTU/hr/ft <sup>2</sup> / F/in.	8.0
Volume Resistivity, OHM-CM	1.0 x 10 <sup>14</sup>
Maximum Operating Temperature:	
Continuous, C°	165
Intermittent, C°	300-400
Lap Shear Strength, psi	4,000

## AVAILABILITY:

50-3120 is available in a variety of syringe sizes and styles. It is also available in quarts, gallons, and 5 gallon pails.

## IMPORTANT:

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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